

MPW #	Geometry	Reservation Close Date*	CDRS Submit Date@	Cancellation Deadline	Dry Run DRC CutOff	Other Participants Tapeout Date#&	Customer Tapeout Date#	Process Offering
MPW8S02	8SW_0.13um	1/4/2021		2/2/2021	2/15/2021	2/15/2021	3/1/2021	8SW
MPW3A01	0.13um_200mm	1/18/2021	1/25/2021	2/16/2021	3/1/2021	3/1/2021	3/15/2021	F35_130UM_BCDSOI
MPW1427	12nm	1/20/2021	1/27/2021	2/17/2021	3/3/2021	3/3/2021	3/17/2021	12LP
MPW2239	22nm	1/25/2021	2/1/2021	2/22/2021	3/8/2021	3/8/2021	3/22/2021	22FDX/22FDX-ATV/22eMRAM. Projected ship dates are for NON-22eMRAM.
MPW06A0	55nm	2/1/2021	2/8/2021	3/2/2021	3/15/2021	3/15/2021	3/29/2021	55LPX/55LPe/55ULP/55BCDL/55NVM
MPW18G3	0.18um	2/1/2021	2/8/2021	3/2/2021	3/15/2021	3/15/2021	3/29/2021	Fab35_IC/BCDlite/UHV/MCU
MPW13B5	0.11/0.13um	2/15/2021	2/22/2021	3/15/2021	3/29/2021	3/29/2021	4/12/2021	RFSOI/BCDlite/BCD
MPW4C00	45SPCLO_45nm	2/17/2021	2/24/2021	3/17/2021	3/31/2021	3/31/2021	4/14/2021	45SPCLO
MPW8N02	130NSX1_0.13um	2/17/2021		3/18/2021	3/31/2021	3/31/2021	4/14/2021	130NSX1

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MPW0363	28nm	2/22/2021	3/1/2021	3/23/2021	4/5/2021	4/5/2021	4/19/2021	28SLP/28SLPe/28SLP-RF/28SLP-HV/28SLP-ESF3
MPW8X05	8XP_0.13um	2/24/2021		3/24/2021	4/7/2021	4/7/2021	4/21/2021	8XP
MPW06A1	65nm	3/1/2021	3/8/2021	3/30/2021	4/12/2021	4/12/2021	4/26/2021	65G/65LPE
MPW0467	40nm	3/8/2021	3/15/2021	4/6/2021	4/19/2021	4/19/2021	5/3/2021	40LP/40LP-ESF3/40RF
MPW9W07	9WG_90nm	3/17/2021		4/14/2021	4/28/2021	4/28/2021	5/12/2021	9WG
MPW2240	22nm	3/29/2021	4/5/2021	4/26/2021	5/10/2021	5/10/2021	5/24/2021	22FDX/22FDX-ATV/22eMRAM. Projected ship dates are for NON-22eMRAM.
MPW9H10	9HP_90nm	3/31/2021		4/28/2021	5/12/2021	5/12/2021	5/26/2021	9HP
MPW06A2	55nm	4/5/2021	4/12/2021	5/4/2021	5/17/2021	5/17/2021	5/31/2021	55LPX/55LPe/55ULP/55BCDL/55HV
MPW1511	0.15um	4/12/2021	4/19/2021	5/11/2021	5/24/2021	5/24/2021	6/7/2021	F35_MCU
MPW5P01	5PA4_0.35um	4/14/2021		5/12/2021	5/26/2021	5/26/2021	6/9/2021	5PA4
MPW13B6	0.11/0.13um	4/19/2021	4/26/2021	5/18/2021	5/31/2021	5/31/2021	6/14/2021	RFSoI/G/LP/EEPROM/110TS/BCDlite/BCD
MPW18G4	0.18um	4/26/2021	5/3/2021	5/25/2021	6/7/2021	6/7/2021	6/21/2021	Fab35_IC/BCDlite/UHV/MCU

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MPW3A02	0.13um_200mm	5/10/2021	5/17/2021	6/8/2021	6/21/2021	6/21/2021	7/5/2021	F35_130UM_BCDSOI
MPW0364	28nm	5/17/2021	5/24/2021	6/15/2021	6/28/2021	6/28/2021	7/12/2021	28SLP/28SLPe/28SLP-RF/28SLP-HV/28SLP-ESF3
MPW4C01	45SPCLO_45nm	5/19/2021	5/26/2021	6/16/2021	6/30/2021	6/30/2021	7/14/2021	45SPCLO
MPW4R08	45RFSOI_45nm	5/19/2021		6/16/2021	6/30/2021	6/30/2021	7/14/2021	45RF
MPW2241	22nm	5/24/2021	5/31/2021	6/21/2021	7/5/2021	7/5/2021	7/19/2021	22FDX/22FDX-ATV
MPW06A3	55nm	5/31/2021	6/7/2021	6/29/2021	7/12/2021	7/12/2021	7/26/2021	55LPX/55LPe/55ULP/55BCDL/55NVM
MPW4E00	45RFE_45nm	6/2/2021	6/9/2021	6/30/2021	7/14/2021	7/14/2021	7/28/2021	45RFE
MPW8X06	8XP_0.13um	6/2/2021		7/1/2021	7/14/2021	7/14/2021	7/28/2021	8XP

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MPW0468	40nm	6/21/2021	6/28/2021	7/20/2021	8/2/2021	8/2/2021	8/16/2021	40LP/40LP-ESF3/40RF
MPW9H11	9HP_90nm	6/23/2021		7/21/2021	8/4/2021	8/4/2021	8/18/2021	9HP
MPW13B7	0.11/0.13um	6/28/2021	7/5/2021	7/27/2021	8/9/2021	8/9/2021	8/23/2021	RFSOI/BCDlite/BCD
MPW06A4	55nm	7/19/2021	7/26/2021	8/17/2021	8/30/2021	8/30/2021	9/13/2021	55LPX/55LPe/55ULP/55BCDL/55HV
MPW8N03	130NSX1_0.13um	7/21/2021		8/19/2021	9/1/2021	9/1/2021	9/15/2021	130NSX1
MPW2242	22nm	7/26/2021	8/2/2021	8/23/2021	9/6/2021	9/6/2021	9/20/2021	22FDX/22FDX-ATV/22eMRAM. Projected ship dates are for NON-22eMRAM.
MPW18G5	0.18um	7/26/2021	8/2/2021	8/24/2021	9/6/2021	9/6/2021	9/20/2021	Fab35_IC/BCDlite/UHV/MCU
MPW06A5	65nm	7/26/2021	8/2/2021	8/24/2021	9/6/2021	9/6/2021	9/20/2021	65G/65LPE

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MPW1512	0.15um	8/9/2021	8/16/2021	9/7/2021	9/20/2021	9/20/2021	10/4/2021		F35_MCU
MPW13B8	0.11/0.13um	8/16/2021	8/23/2021	9/14/2021	9/27/2021	9/27/2021	10/11/2021		RFSoI/G/LP/EEPROM/110TS/BCDlite/BCD
MPW0365	28nm	8/16/2021	8/23/2021	9/14/2021	9/27/2021	9/27/2021	10/11/2021		28SLP/28SLPe/28SLP-RF/28SLP-HV/28SLP-ESF3
MPW4C02	45SPCLO_45nm	8/18/2021	8/25/2021	9/15/2021	9/29/2021	9/29/2021	10/13/2021		45SPCLO
MPW5P02	5PA4_0.35um	8/18/2021		9/15/2021	9/29/2021	9/29/2021	10/13/2021		5PA4
MPW8S04	8SW_0.13um	8/23/2021		9/21/2021	10/4/2021	10/4/2021	10/18/2021		8SW
MPW8X07	8XP_0.13um	8/25/2021		9/23/2021	10/6/2021	10/6/2021	10/20/2021		8XP
MPW9H12	9HP_90nm	9/8/2021		10/6/2021	10/20/2021	10/20/2021	11/3/2021		9HP
MPW0469	40nm	9/14/2021	9/21/2021	10/12/2021	10/26/2021	10/26/2021	11/8/2021		40LP/40LP-ESF3/40RF
MPW4R09	45RFSoI_45nm	9/15/2021		10/13/2021	10/27/2021	10/27/2021	11/10/2021		45RF
MPW06A6	55nm	9/21/2021	9/28/2021	10/19/2021	11/2/2021	11/2/2021	11/15/2021		55LPX/55LPe/55ULP/55BCDL/55NVM

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MPW2243	22nm	9/27/2021	10/4/2021	10/25/2021	11/8/2021	11/8/2021	11/22/2021	22FDX/22FDX-ATV
MPW18G6	0.18um	10/11/2021	10/18/2021	11/8/2021	11/22/2021	11/22/2021	12/6/2021	Fab35_IC/BCDlite/UHV/MCU

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